APPLICA	BLE STAN	IDARD										
	OPERATING TEMPERATURE RANGE		-35 °C TO +85 °C(NOTES		STORA TEMPE		IRE RANC	ΞE	-10 °C TO +60 °C(NOTE2)			
RATING	VOLTAGE		250 V AC		APPLIC	PERATURE RANGE			DF1E- * S-2. 5C		_,	
	CURRENT		AWG20 TO 24: 3A				OLTAGE		AC 30V			
	CORRENT		AWG26: 24		UL, CS				AU 300 AWG20 TO 22:			
			AWG28: 1A		UL, U		JRRENT	-	AWG24 TO 28:	3A 1A		
			AWG30: 0.5	A					AWG30: 0.). 5A	
			SPEC	IFICA	TION	S						
TI	EM	TEST METHOD				REQUIREMENTS				QT	AT	
CONSTRUCTION												
		VISUALLY AND BY MEASURING INSTRUMENT.			NT. A	ACCORDING TO DRAWING.				Х	Х	
										Х	Х	
	IC CHARA					0 0				- <u>-</u>		
MILLIVOLT LEVEL METHOD.		20 mV MAX, 1 mA(DC OR 1000 Hz).				30 mΩ MAX.				X	-	
INSULATION RESISTANCE		500 V DC.				1000 MΩ MIN.				X	-	
VOLTAGE PROOF		650 V AC FOR 1 min.				NO FLASHOVER OR BREAKDOWN.				Х	_	
_	IICAL CHA	-			I						<u> </u>	
MECHANICAL OPERATION		50 TIMES INSERTIONS AND EXTRACTIONS.				 CONTACT RESISTANCE: 30 mΩ MAX. NO DAMAGE, CRACK OR LOOSENESS OF PARTS. 				x	_	
VIBRATION		0.75 mm, AT 2 h, FOR 3 DIRECTIONS.				 ① NO ELECTRICAL DISCONTINUITY OF 1 μs. ② NO DAMAGE, CRACK OR LOOSENESS OF PARTS. X 				x	_	
SHOCK		490 m/s ² DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.								_		
			ACTERISTICS									
RAPID CHANGE OF TEMPERATURE		TIME $30 \rightarrow 5 \text{ MAX} \rightarrow 30 \rightarrow 5 \text{ MAX} \text{ min}$				 CONTACT RESISTANCE: 30 mΩ MAX. INSULATION RESISTANCE: 1000 MΩ MIN. NO DAMAGE, CRACK OR LOOSENESS OF PARTS. 				x	-	
DAMP HEAT (STEADY STATE)						 CONTACT RESISTANCE: 30 mΩ MAX. INSULATION RESISTANCE: 500 MΩ MIN. NO DAMAGE, CRACK OR LOOSENESS OF PARTS. 				x	-	
RESISTANCE TO		1) AUTOMATIC SOLDERING (FLOW)				NO DEFORMATION OF CASE OF EXCESSIVE						
SOLDERING HEAT		SOLDER TEMPERATURE, 260 °C FOR IMMERSION, DURATION, 10 sec. 2) MANUAL SOLDERING SOLDERING IRON TEMPERATURE : 300 °C, SOLDERING TIME : 3 sec. NO STRENGTH ON CONTACT.				LOOSENESS OF THE TERMINALS.				X	-	
SOLDERABILITY		SOLDER	SOLDERED AT SOLDER TEMPERATURE, 235 °C FOR IMMERSING DURATION, 5 s.				SOLDER SHALL COVER A MINIMUM OF 95 % OF THE SURFACE BEING IMMERSED.				_	
	T DI	SCRIPTIC	ON OF REVISIONS		DESIGN	ED			CHECKED	DA	ΔTE	
<u>ZUN</u> REMARKS												
NOTE1: INCLU	JDE THE TEMP	ERATURE F	RATURE RISING BY CURRENT. FION OF LONG TERM STORAGE FOR UNUSED PRODUCT: RD,AFTER PCB BOARD,OPERATING TEMPERATURE AND PPLIED FOR INTERIM STORAGE DURING TRANSPORTATI of rofer to JEC 60512				APPRO	VED	KI.AKIYAMA	15.0	15. 05. 23	
NOTE2:NO CO NOTE3:APPL`		DITION OF L				DEGLONIE		KED	TS. FUKUSHIMA 1)5. 23	
HUMIE	DITY RANGE IS	APPLIED FO						NED	TS. KUMAZAWA	IAZAWA 15.05.		
Unless otherwise specified, refer						DRAWN		VN	MI. SAKIMURA	15. 05. 23		
Note QT:Qualification Test AT:As			surance Test X:Applicable Test DI			RAWING NO.			ELC-161943-36-00			
HIROSE E						RT NO.		DF	1EC-*P-2. 5DSA (36	i)		
			LECTRIC CO., LTD. CODE			NO.			CL541		1/1	
ORM HDOO11	0 1											

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